

95-317920/41	A85103 (A26)	SUMM 94.01.28
SUMITOMO METAL MINING CO	*JP 07216553-A	
94.01.28 94JP-008535 (95.08.15)	C23C 18/28, B32B 15/08, C25D 5/12,	A/5-11, 11-C4B1, 11-C4D, 12-S6B) 1/3-H4E1, 3-H4E3, 4-C24A)
H05K 3/28	Prodn. of copper-coated polyimide substrate - by etching surface of polyimide resin film, surface-treating with alkali soln., applying catalyst, activating, electroless plating, heat-treating, and forming	ADVANTAGE Polyimide resin film has high adhesion strength even with thick polyimide resin film. (4pp003DwgNo.0/0)(NA) (4ppDwgNo.0/0)
C95-141368	The prodn. of Cu-coated polyimide substrates comprises subjecting the surface of the polyimide resin film to etching, and then surface-treating with an alkali soln. of concn. 0.1-5 mol/l at 0-50° C, applying a catalyst for electroless plating; activating the applied catalyst; electroless-plating one of Ni, Co or other metal alloy; heat-treating the obtd. plated material in an inert atmos.; and forming electro-Cu plating on the electroless plating layer. Na hydroxide soln. or K hydroxide soln. is used as the alkali soln..	
USE	Used to produce Cu-coated polyimide substrates for printed-writing boards (PWB), e.g., flexible printed circuit (FPC) or tape-automatic bonding (TAB) tape.	
		JP 07216553-A